

A<sup>2</sup>  
Cont'd.

**SECRET**

**SECRET**

**SECRET**

**SECRET**

**SECRET**

**SECRET**

**SECRET**

**SECRET**

Preliminary Amendment  
U.S. Appln. No. Unknown

12  
Cont'd.  
5. ~~27~~ The method of making an interconnectable package of claim 26, wherein the integrated circuit is an millimeter microwave integrated circuit.

6. ~~28~~ The method of making an interconnectable package of claim 23, wherein the component is an optical fiber.

7. ~~29~~ The method of making an interconnectable package of claim 23, wherein the component is an optical semiconductor.

8. ~~30~~ The method of making an interconnectable package of claim 23, wherein the integral connector etched on said top die of said second wafer is shaped as a male connection component.

9. ~~31~~ The method of making an interconnectable package of claim 23, wherein the integral connected etched on said top die of said second wafer is shaped as a female connection component.

10. ~~32~~ The method of making an interconnectable package of claim 23, wherein the integral connected etched on said top die of said second wafer is shaped as a hermaphrodite connection component.

11. ~~33~~ The method of making an interconnectable package of claim 23, wherein the integral connected etched on said top die of said second wafer is shaped as a female connection component.

Preliminary Amendment  
U.S. Appln. No. Unknown

*A2  
Cont'd.  
Index*

12.34. A method of making a dielectric package for housing a component and having an integral connection member comprising:

- providing a first die having at least one conductor patterned on the die;
- providing a second die having at least one conductor patterned on said second die;
- bonding said second die to said first die such that the conductor on said first die is aligned with said conductor on said second die.

13.35. The method of making a dielectric package for housing a component and having an integral connection member of claim 34, wherein the first die is formed having a female shape.

14.36. The method of making a dielectric package for housing a component and having an integral connection member of claim 34, wherein the second die is formed having a male shape.

15.37. The method of making a dielectric package for housing a component and having an integral connection member of claim 36, further comprising:

coupling a component to said first die prior to bonding the second die to said first die.

16.38. The method of making a dielectric package for housing a component and having an integral connection member of claim 34, further comprising:

etching an aperture into said second die.

**Preliminary Amendment**  
**U.S. Appl. No. Unknown**

39. The method of making as dielectric package for housing a component and having an integral connection member of claim 38, wherein a component is placed through said aperture on said second die and coupled to said first die after the second die is bonded to the first die.

~~38. 40. The method of making as dielectric package for housing a component and having an integral connection member of claim 34, wherein the component is an integrated circuit.~~

~~9, 41.~~ The method of making a dielectric package for housing a component and having an integral connection member of claim 40, wherein the integrated circuit is a millimeter microwave integrated circuit.

20,42. The method of making a dielectric package for housing a component and having an integral connection member of claim 34, wherein the component is an optical fiber.

21. 43. The method of making a dielectric package for housing a component and having an integral connection member of claim 34, wherein the component is an optical semiconductor.